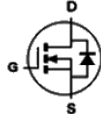


PDFN5*6

Symbol


Parameter	Value	Unit
V_{DS}	30	V
$R_{DS(ON)-Max}$	4	m Ω
I_D	70	A

Key Features

- Reliable and Rugged
- ROHS Compliant & Halogen-Free
- Lower Q_g and Q_{gd} for high-speed switching
- Lower $R_{DS(ON)}$ to Minimize Conduction Losses
- 100% UIS and R_g Tested

Applications

- Power Management in DC/DC Converters
- Power Load Switch
- Notebook Battery Management

Ordering Information

Ordering part Number	Marking code	Package	Form
VPLMDF7141	7141	PDFN5*6	Tape & Reel

Absolute Maximum Ratings ($T_J = 25^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 20	V
Maximum Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature Range	T_{STG}	-55 to 150	$^\circ\text{C}$
Pulse Drain Current Tested	$T_C = 25^\circ\text{C}$ $I_{DM}^{(1)}$	70	A
Continuous Drain Current	$T_C = 25^\circ\text{C}$ $I_D^{(2)}$	70	A
	$T_C = 100^\circ\text{C}$	50	
Maximum Power Dissipation	$T_C = 25^\circ\text{C}$ $P_D^{(2)}$	46	W
	$T_C = 100^\circ\text{C}$	18	
Avalanche Current, Single pulse	$L = 0.1\text{mH}$ $I_{AS}^{(3)}$	31	A
Avalanche Energy, Single pulse	$L = 0.1\text{mH}$ $E_{AS}^{(3)}$	48	mJ

Thermal Characteristics

Parameter	Symbol	Rating	Unit
Thermal Resistance-Junction to Case	Steady State $R_{\theta JC}$	2.7	$^\circ\text{C/W}$
Thermal Resistance-Junction to Ambient	Steady State $R_{\theta JA}^{(3)}$	50	$^\circ\text{C/W}$

- ⁽¹⁾ Max. current is limited by bonding wire
- ⁽²⁾ UIS tested and pulse width are limited by maximum junction temperature 150°C
- ⁽³⁾ Surface Mounted on 1in^2 FR-4 board with 1oz.

Electrical Characteristics ($T_J = 25^\circ\text{C}$, unless otherwise specified)

Static Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	30	-	-	V	$V_{GS}=0V, I_{DS}=250\mu A$
Zero Gate Voltage Drain Current	I_{DSS}	-	-	1	μA	$V_{DS}=24V, V_{GS}=0V$
Gate Threshold Voltage	$V_{GS(th)}$	1	1.5	2	V	$V_{DS}=V_{GS}, I_{DS}=250\mu A$
Gate Leakage Current	I_{GSS}	-	-	± 100	nA	$V_{GS}=\pm 20V, V_{DS}=0V$
Drain-Source On-state Resistance	$R_{DS(ON)}^{(4)}$	-	3.4	4	m Ω	$V_{GS}=10V, I_{DS}=20A$
		-	4.5	6		$V_{GS}=4.5V, I_{DS}=10A$
Forward Transconductance	g_{fs}	-	25.2	-	S	$V_{DS}=5V, I_{DS}=20A$

Dynamic Characteristics⁽⁵⁾

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Gate Resistance	R_G	-	1	-	Ω	$V_{GS}=0V, V_{DS}=0V,$ Freq.=1MHz
Input Capacitance	C_{iss}	-	2435	-	pF	$V_{GS}=0V, V_{DS}=15V,$ Freq.=1MHz
Output Capacitance	C_{oss}	-	308	-		
Reverse Transfer Capacitance	C_{rss}	-	259	-		
Turn-on Delay Time	$t_{d(ON)}$	-	10.3	-	nS	$V_{GS}=10V, V_{DS}=15V,$ $I_D=1A, R_{GEN}=3\Omega$
Turn-on Rise Time	t_r	-	17.6	-		
Turn-off Delay Time	$t_{d(OFF)}$	-	43.2	-		
Turn-off Fall Time	t_f	-	31.7	-		

Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Total Gate Charge	Q_g	-	33	-	nC	$V_{GS}=4.5V, V_{DS}=15V,$ $I_D=20A$
		-	62	-		$V_{GS}=10V, V_{DS}=15V,$ $I_D=20A$
Gate-Source Charge	Q_{gs}	-	10.19	-		
Gate-Drain Charge	Q_{gd}	-	16.01	-		

Source Drain Diode Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Diode Forward Voltage	$V_{SD}^{(4)}$	-	0.7	1.1	V	$I_{SD}=1A, V_{GS}=0V$
Reverse Recovery Time	t_{rr}	-	20	-	nS	$I_F=1A, V_{GS}=0$ & $di_F/dt=100A/\mu s$
Reverse Recovery Charge	Q_{rr}	-	12	-	nC	

- ⁽⁴⁾ Pulse test (pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$).
- ⁽⁵⁾ Guaranteed by design, not subject to production test

Electrical Characteristics Diagrams

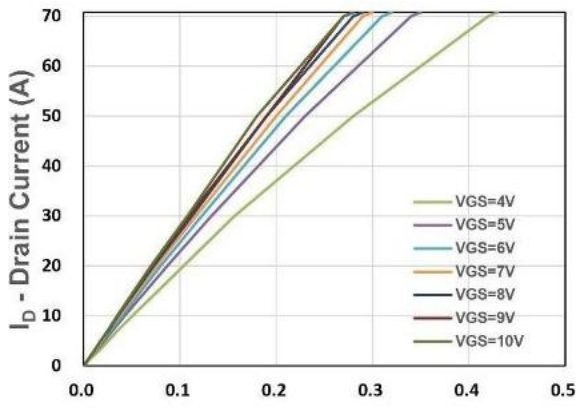


Figure 1. Output Characteristics

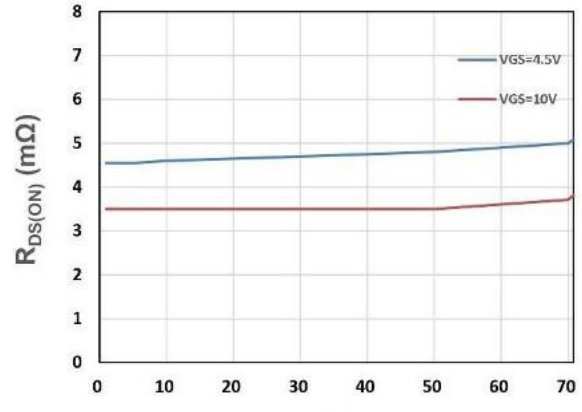


Figure 2. On-Resistance vs. I_D

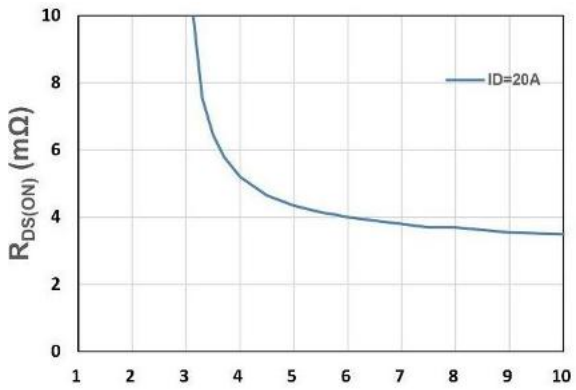


Figure 3. On-Resistance vs. V_{GS}

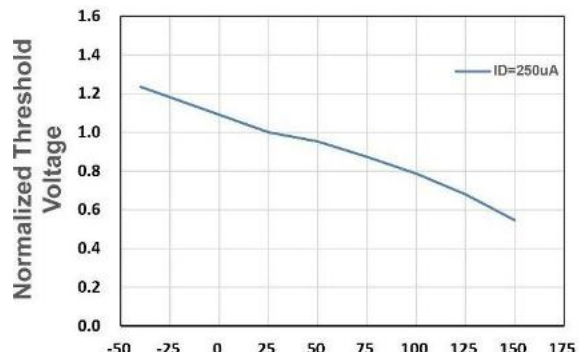


Figure 4. Gate Threshold Voltage

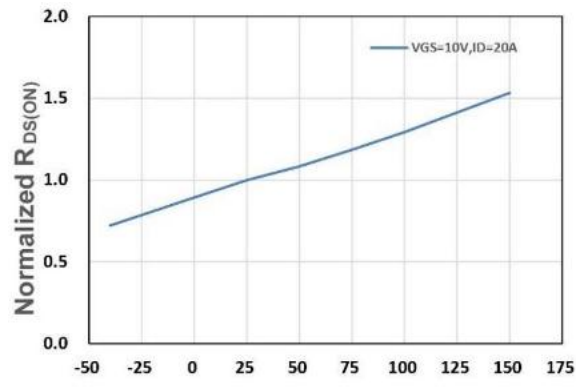


Figure 5. Drain-Source On Resistance

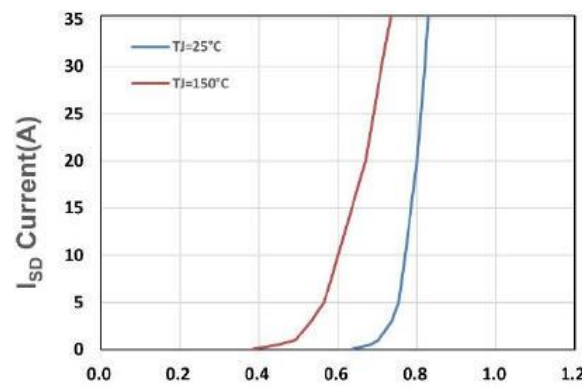
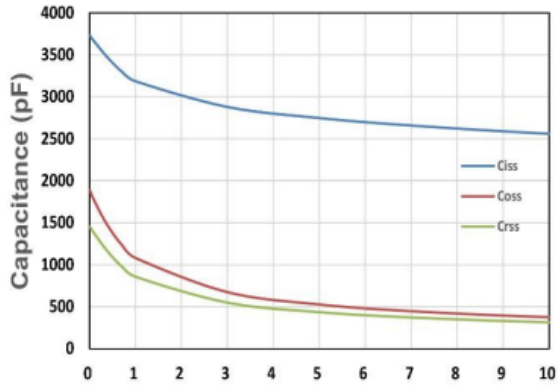
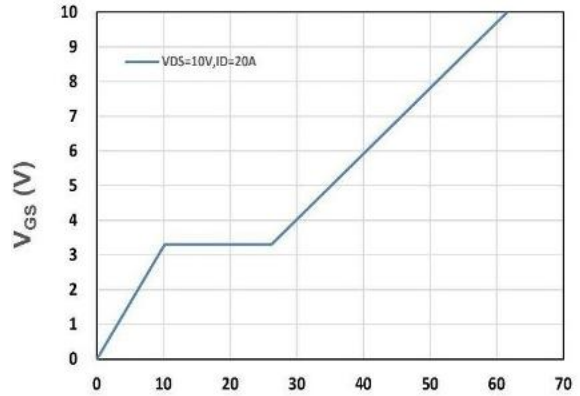


Figure 6. Source-Drain Diode Forward



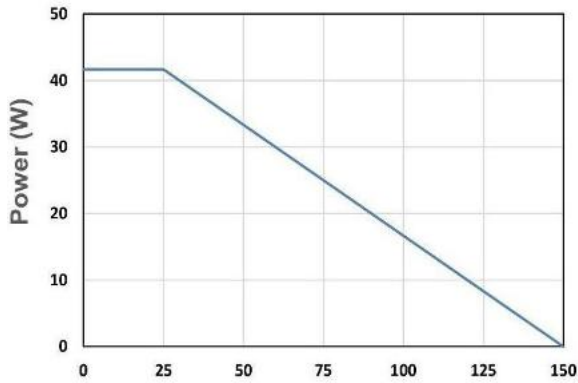
V_{DS} - Drain - Source Voltage (V)

Figure 7. Capacitance



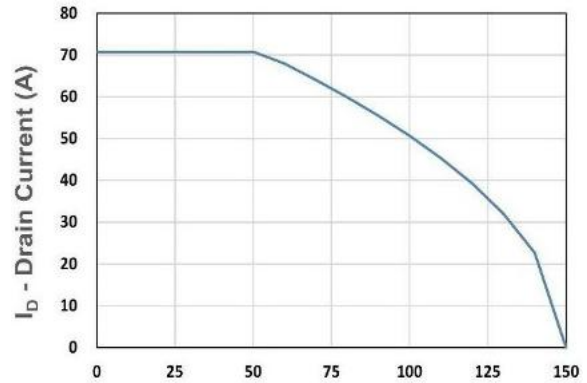
Q_g , Total Gate Charge (nC)

Figure 8. Gate Charge Characteristics



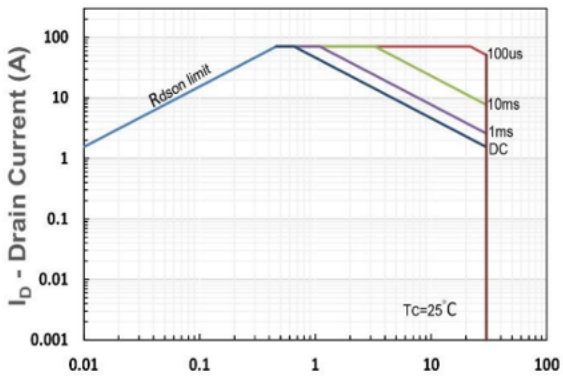
T_C - Case Temperature (°C)

Figure 9. Power Dissipation



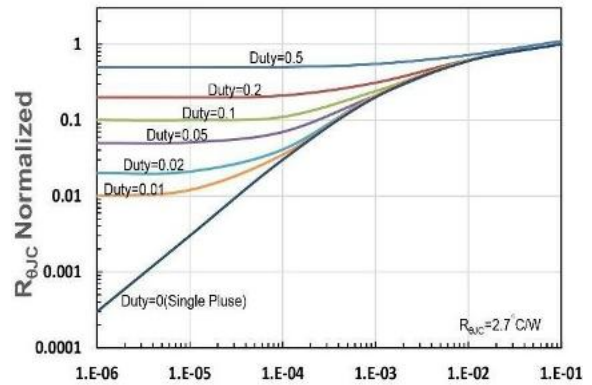
T_C - Case Temperature (°C)

Figure 10. Drain Current



V_{DS} - Drain-Source Voltage (V)

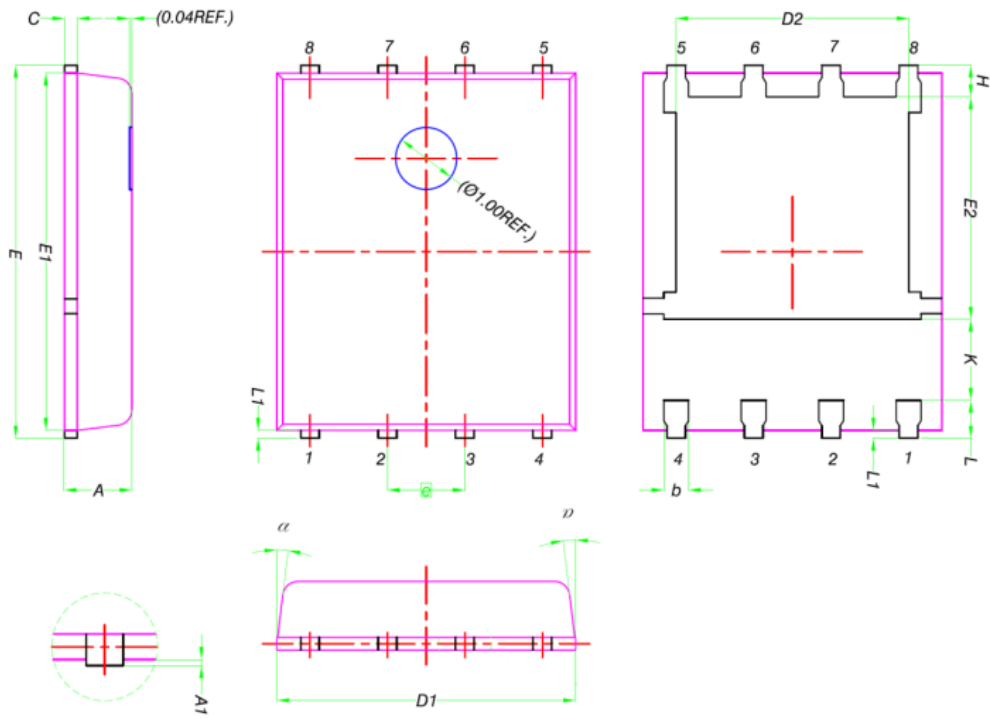
Figure 11. Safe Operating Area



t_1 , Square Wave Pulse Duration (s)

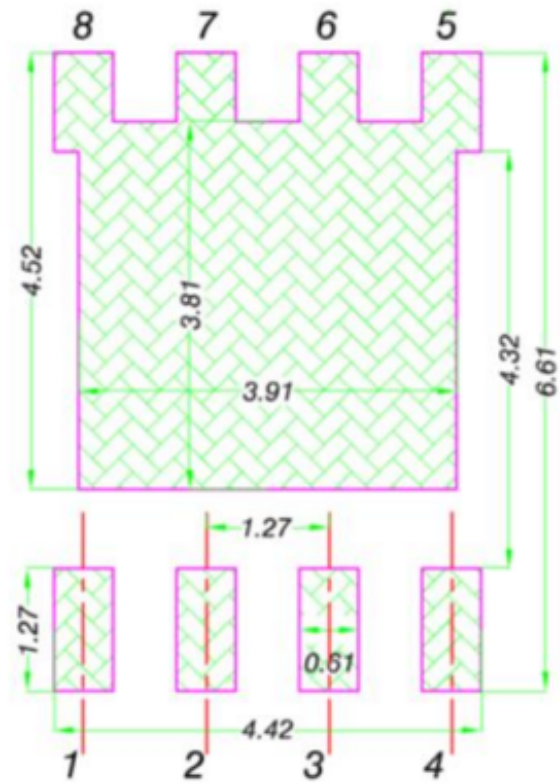
Figure 12. $R_{\theta JC}$ Transient Thermal Impedance

Package Information (PDFN5*6)



Outline dimensions in mm

Unit:mm	Min	Typ	Max
A	0.900	1.000	1.100
A1	0.000	-	0.050
b	0.330	0.410	0.510
C	0.200	0.250	0.300
D1	4.800	4.900	5.000
D2	3.610	3.810	3.960
E	5.900	6.000	6.100
E1	5.700	5.750	5.800
E2	3.380	3.580	3.780
e	1.27 BSC		
H	0.410	0.510	0.610
K	1.100	-	-
L	0.510	0.610	0.710
L1	0.060	0.130	0.200
α	0°	-	12°



Suggested Pad Layout (Unit:mm)

Disclaimer

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